



SOLDER SPHERE  
95.5% Sn/4% Ag/0.5%Cu  
0.61 DIA. 388 PLACES

1	SOCKET ASM.	Advanced Interconnections	#9173LFTR	
ITEM	QTY	NAME	MATERIAL	DESCRIPTION
Parts List				
FILE NAME		LFBGARBVA0.dwg		
CONTRACT NO		-		
DRAWN		10/29/07 CJW		
CHECK				
APPR.		06/14/2010 = WEB		
ISSUED				
NOTE:		DIMENSIONS ARE IN MILLIMETERS DO NOT SCALE DRAWING		
SIZE	FSCM NO	DWG NO	REV	
B	-	LFBGARBVA0		
SCALE	2:1	WEIGHT	SHEET 1 of 1	



NXP Semiconductors  
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BGA Base with Receivers  
388 Pin 1.0mm Pitch (Lead Free)